

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.01177	100.0	0.28
			<b>Subtotal</b>	<b>0.01177</b>	<b>100</b>	<b>0.28</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00076	2.0	0.018
	Lead alloy	Silver (Ag)	7440-22-4	0.00095	2.5	0.0225
	Lead alloy	Lead (Pb)	7439-92-1	0.03612	95.5	0.8595
			<b>Subtotal</b>	<b>0.03783</b>	<b>100</b>	<b>0.9</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0102	0.03	0.2427
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.0102	0.03	0.2427
	Copper alloy	Iron (Fe)	7439-89-6	0.03399	0.1	0.809
	Copper alloy	Copper (Cu)	7440-50-8	33.93893	99.84	807.7056
			<b>Subtotal</b>	<b>33.99332</b>	<b>100</b>	<b>809</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.21035	8.0	124
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.51293	10.0	155
	Filler	Silica fused	60676-86-0	52.10348	80.0	1,240
	Flame retardant	Metal hydroxide		1.30259	2.0	31
			<b>Subtotal</b>	<b>65.12935</b>	<b>100</b>	<b>NaN</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.6723	100.0	16
			<b>Subtotal</b>	<b>0.6723</b>	<b>100</b>	<b>16</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.03124	100.0	0.74353
	Pure metal	Aluminium (Al)	7429-90-5	0.12421	100.0	2.956
			<b>Subtotal</b>	<b>0.15545</b>	<b>200</b>	<b>3.69953</b>
			<b>Total</b>	<b>100.00002</b>	<b>100</b>	<b>NaN</b>

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